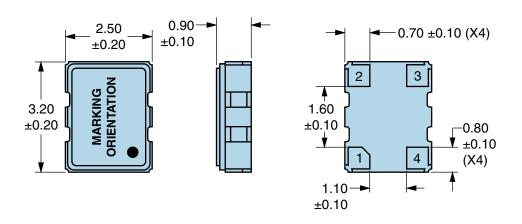


ELECTRICAL SPECIFICATIONS			
Nominal Frequency	40.000MHz		
Frequency Stability vs. Frequency Tolerance	±0.5ppm Maximum (at 25°C ±2°C, at Vdd=3.0Vdc, and Vc=1.5Vdc)		
Frequency Stability	±2.0ppm Maximum (Inclusive of Operating Temperature Range, At Vdd=3.0Vdc and Vc=1.5Vdc)		
Frequency Stability vs. Input Voltage	±0.2ppm Maximum (±5%)		
Frequency Stability vs. Aging	±1ppm/year Maximum (at 25°C)		
Frequency Stability vs. Load	±0.2ppm Maximum (±1kOhm//±1pF)		
Operating Temperature Range	-20°C to +70°C		
Supply Voltage	+3.0Vdc ±5%		
Input Current	2.5mA Maximum		
Output Voltage	0.8Vp-p Clipped Sinewave Minimum (External DC-Cut capacitor required, 1000pF recommended)		
Load Drive Capability	10kOhms//10pF		
Output Logic Type	Clipped Sinewave		
Control Voltage	1.5Vdc ±1.0Vdc		
Frequency Deviation	±8ppm Minimum		
Transfer Function	Positive Transfer Characteristic		
Phase Noise	-80dBc/Hz at 10Hz Offset, -115dBc/Hz at 100Hz Offset, -135dBc/Hz at 1kHz Offset, and -148dBc/Hz at 10kHz Offset (Typical Values at 16.368MHz)		
Start Up Time	5mSec Maximum		
Storage Temperature Range	-55°C to +125°C		

ENVIRONMENTAL & MECHANICAL SPECIFICATIONS		
Fine Leak Test	MIL-STD-883, Method 1014 Condition A	
Gross Leak Test	MIL-STD-883, Method 1014 Condition C	
Mechanical Shock	MIL-STD-202, Method 213 Condition C	
Resistance to Soldering Heat	MIL-STD-202, Method 210	
Resistance to Solvents	MIL-STD-202, Method 215	
Solderability	MIL-STD-883, Method 2003	
Temperature Cycling	MIL-STD-883, Method 1010	
Vibration	MIL-STD-883, Method 2007 Condition A	



MECHANICAL DIMENSIONS (all dimensions in millimeters)

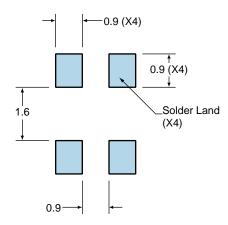


PIN	CONNECTION
1	Voltage Control
2	Case/Ground
3	Output
4	Supply Voltage

LINE	MARKING
1	EXX.XXX E=Ecliptek XX.XXX=Nominal Frequency in MHz (5 Digits Maximum + Decimal)
2	XXYZZ XX=Ecliptek Manufacturing Code Y=Last Digit of the Year ZZ=Week of the Year

Suggested Solder Pad Layout

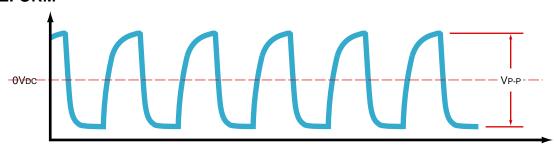
All Dimensions in Millimeters



All Tolerances are ±0.1

OUTPUT WAVEFORM

CLOCK OUTPUT





Recommended Solder Reflow Methods



High Temperature Infrared/Convection

T _s MAX to T _∟ (Ramp-up Rate)	3°C/second Maximum
Preheat	
- Temperature Minimum (Ts MIN)	150°C
- Temperature Typical (T _s TYP)	175°C
- Temperature Maximum (T _s MAX)	200°C
- Time (t _s MIN)	60 - 180 Seconds
Ramp-up Rate (T _L to T _P)	3°C/second Maximum
Time Maintained Above:	
- Temperature (T∟)	217°C
- Time (t∟)	60 - 150 Seconds
Peak Temperature (T _P)	260°C Maximum for 10 Seconds Maximum
Target Peak Temperature (T _P Target)	250°C +0/-5°C
Time within 5°C of actual peak (tp)	20 - 40 seconds
Ramp-down Rate	6°C/second Maximum
Time 25°C to Peak Temperature (t)	8 minutes Maximum
Moisture Sensitivity Level	Level 1



Recommended Solder Reflow Methods



Low Temperature Infrared/Convection 240°C

T _S MAX to T _L (Ramp-up Rate)	5°C/second Maximum
Preheat	
- Temperature Minimum (T _s MIN)	N/A
- Temperature Typical (T _S TYP)	150°C
- Temperature Maximum (T _s MAX)	N/A
- Time (t _s MIN)	60 - 120 Seconds
Ramp-up Rate (T _L to T _P)	5°C/second Maximum
Time Maintained Above:	
- Temperature (T∟)	150°C
- Time (t∟)	200 Seconds Maximum
Peak Temperature (T _P)	240°C Maximum
Target Peak Temperature (T _P Target)	240°C Maximum 1 Time / 230°C Maximum 2 Times
Time within 5°C of actual peak (tp)	10 seconds Maximum 2 Times / 80 seconds Maximum 1 Time
Ramp-down Rate	5°C/second Maximum
Time 25°C to Peak Temperature (t)	N/A
Moisture Sensitivity Level	Level 1

Low Temperature Manual Soldering

185°C Maximum for 10 seconds Maximum, 2 times Maximum.

High Temperature Manual Soldering

260°C Maximum for 5 seconds Maximum, 2 times Maximum.